

POLISHING PAD, METHOD FOR PRODUCING THE SAME AND METHOD OF
FABRICATING SEMICONDUCTOR DEVICE USING THE SAME

ABSTRACT

5

The present invention relates to a polishing pad, a method for producing the same,
and a method of fabricating a semiconductor device using the same. According to the
present invention, it is possible to prevent defects from occurring due to an inorganic
component contained in a polishing layer during a polishing process, by limiting the
10 content range of the inorganic component contained in the polishing layer. In addition, an
unexpanded solid foaming agent is contained in a polishing composition for producing a
polishing layer and is expanded during a curing process to form a plurality of uniform
pores in the polishing layer, and the content range of the inorganic component contained
in the polishing layer, thereby preventing defects from occurring during the polishing
15 process.

[FIG 2]